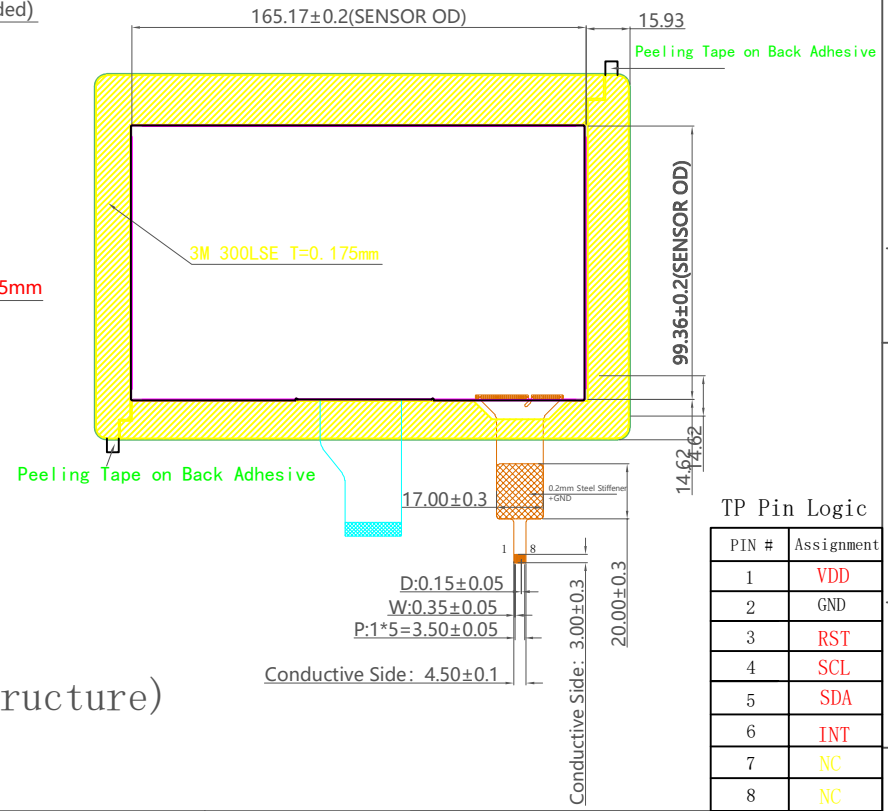
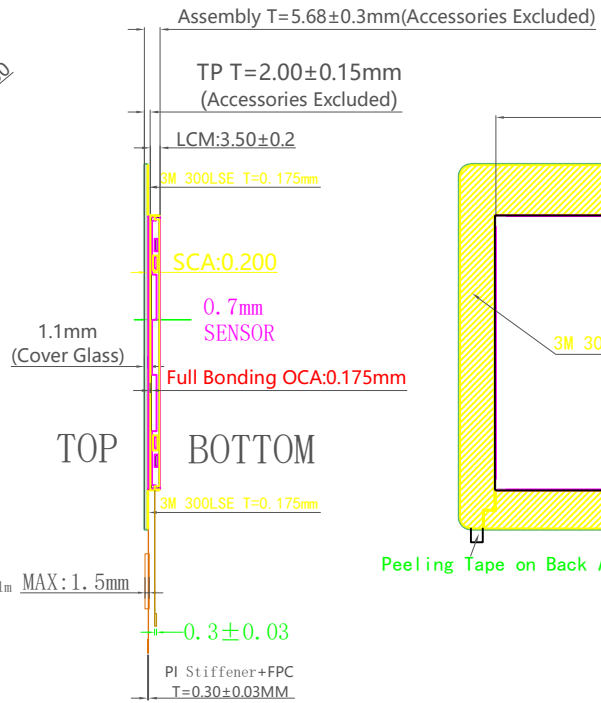
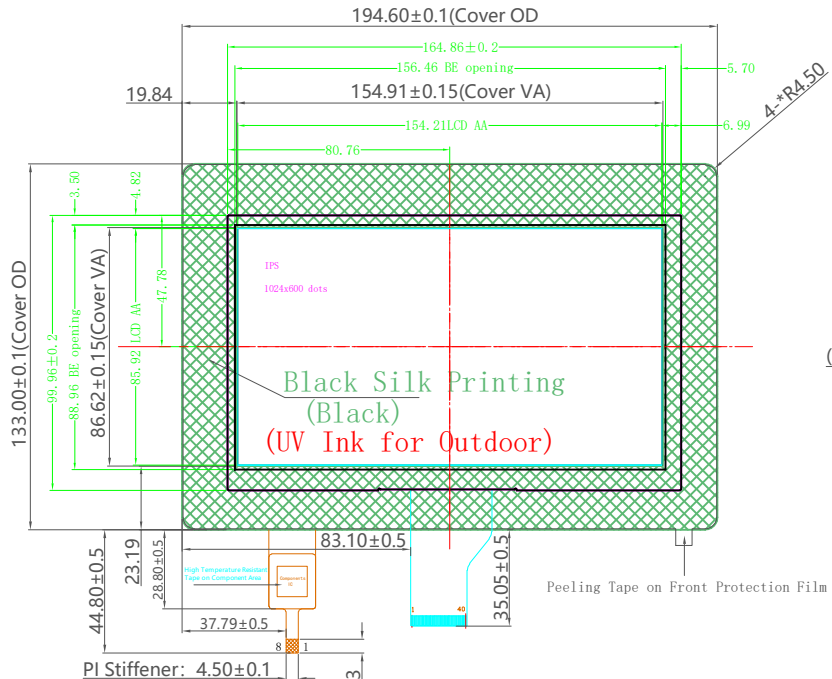


客户签名: _____
日期: _____

Front View Side View Back View



TP Pin Logic

PIN #	Assignment
1	VDD
2	GND
3	RST
4	SCL
5	SDA
6	INT
7	NC
8	NC

(GG+LCM Full Bonding Structure)

Technical Parameters:
1. GLASS+SCA+GlassITO+FPC
2. GG/COF Structure:HY4633, RX12*TX22;
3. Cover Lens Material:Asahi Glass;
Surface Hardness:≥6H
4. Cover Lens Transparency:≥85%
5. Cover Lens Hardness:≥6H
6. TP Operating Environment:-20℃~+70℃, ≤90%RH
7. TP Storage Environment:-30℃~+80℃, ≤90%RH
8. ROHS Compliant
9. Unmarked Tolerance:±0.2mm

物料	NO.	更改内容	日期
	1		
	2		
	3		
	4		
	5		
	6		
	7		

工程确认图

方向	
绘图	审核
	日期
	20220526

MAXEN ELECTRONICS LIMITED

公司编号	MX-B70HL40-IX20H-F1697	未注公差	±0.20
客户编号		单位	mm
版本号		比例	1 : 1

A B C D